

ABSTRACT

To provide an adhesive which is excellent in spin coatability to the circuit surface of a wafer and a support (support substrate), is excellent in heat resistance at the time of bonding the circuit surface of the wafer and the support via an adhesive layer and at the time of processing the back surface of the wafer, and allows for easy peel off of the wafer and the support after processing the wafer (for example, after polishing the back surface of the wafer), and a laminate having the adhesive.

Provided is an adhesive for peelably bonding between a support and a circuit surface of a wafer to allow for processing of a back surface of the wafer, the adhesive including a component (A) that cures through a hydrosilylation reaction and a component (B) containing a polyether-modified siloxane.

[No figure]